

The background of the slide is a photograph of a cleanroom environment. In the foreground, a person wearing a full-body white cleanroom suit, including a hood and gloves, is seated at a workstation. They are looking at two computer monitors. The left monitor displays a software interface with various data points and graphs, while the right monitor shows a high-magnification micrograph of a microfabricated structure. In the background, another person in a similar cleanroom suit is visible, working at another station. The overall atmosphere is sterile and professional, typical of a high-tech manufacturing or research facility.

Inspection and metrology

MICRO-331
Microfabrication
technologies

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M. Gijs
& teams

2022 edition

Inspection and metrology

- Optical inspection
- Thin film characterization
- Electrical characterization
- Advanced techniques (SEM, FIB, AFM)

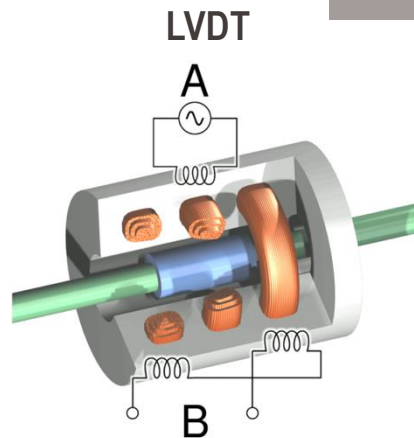
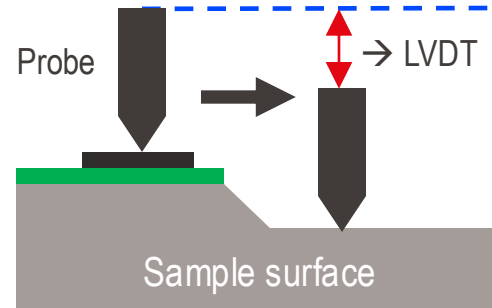
Optical inspection Summary

- Easy, fast and cost-effective method for inspection and dimension measurement
- Multiple modes for specific purpose, colour
- Non-contact, non-invasive
- Works for both opaque and transparent specimens
- Workhorse for sample inspection

Mechanical surface profiler

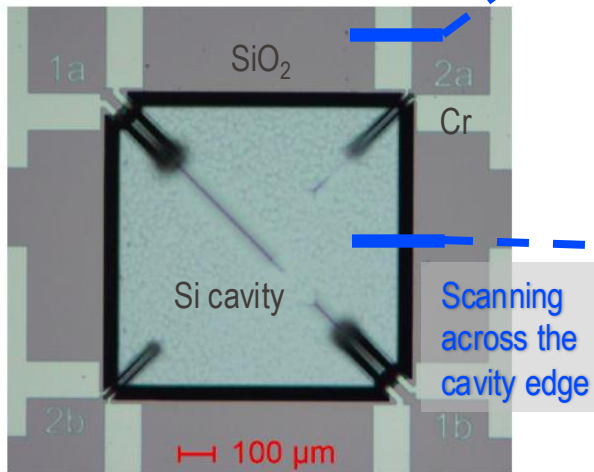
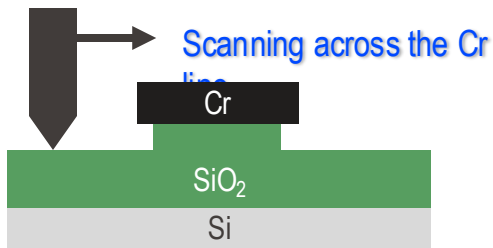
- Diamond probe scans the surface
- Surface height $\rightarrow$ probe position $\rightarrow$ electrical signal
- Resolution in Z: $\sim 1\text{nm}$
- Measurement range in Z: up to 1mm
- Scan length up to 55mm
- Risk to damage the probe or sample

LVDT = linear variable differential transformer

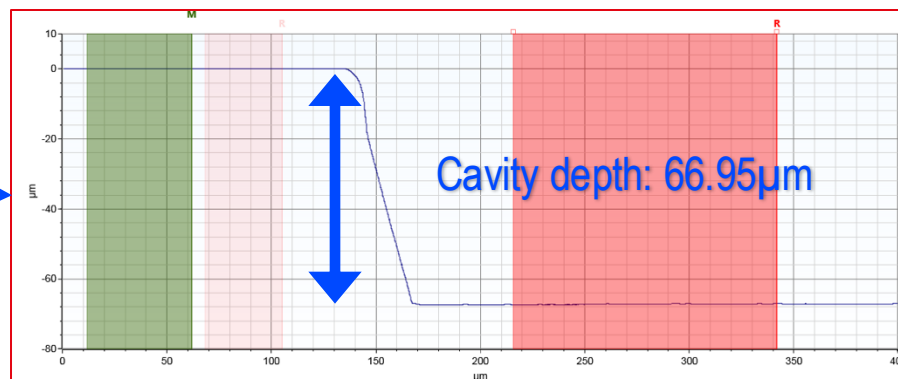
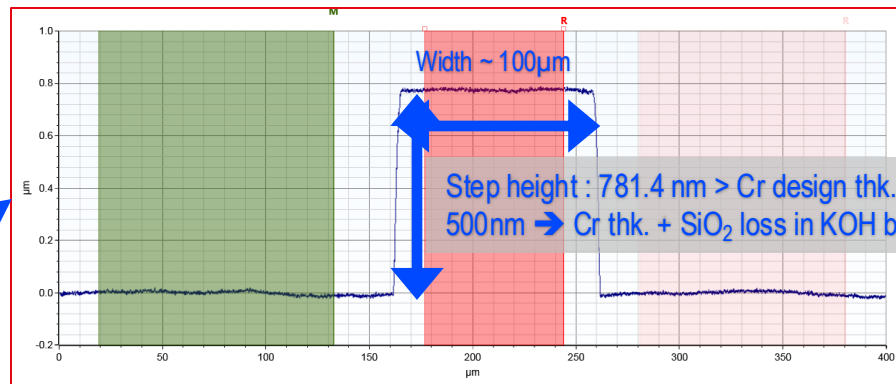


<https://commons.wikimedia.org/wiki/File:LVDT.png>

Surface profile measurement



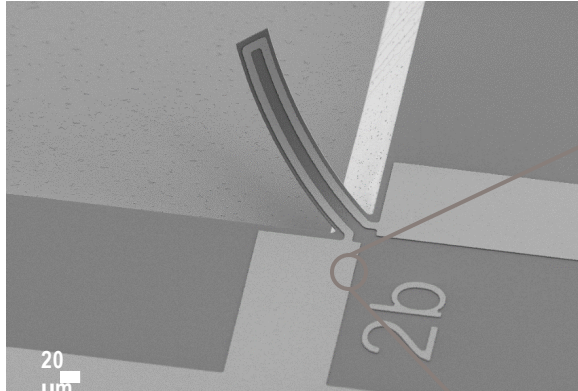
Optical microscope



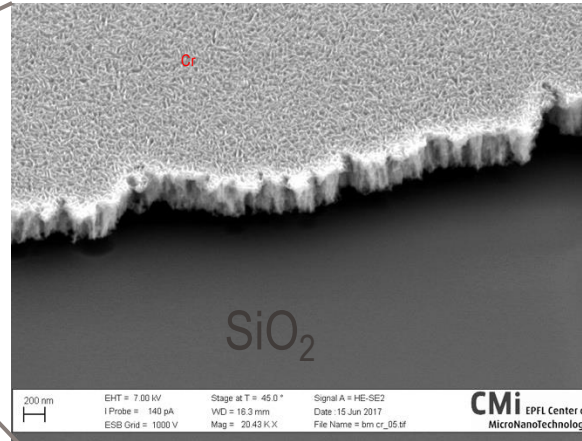
* Please refer to the previous module: **Case study: thermo-mechanical micro-actuator**

Bi-morph surface roughness measurement

- measure the surface roughness of Cr and SiO₂

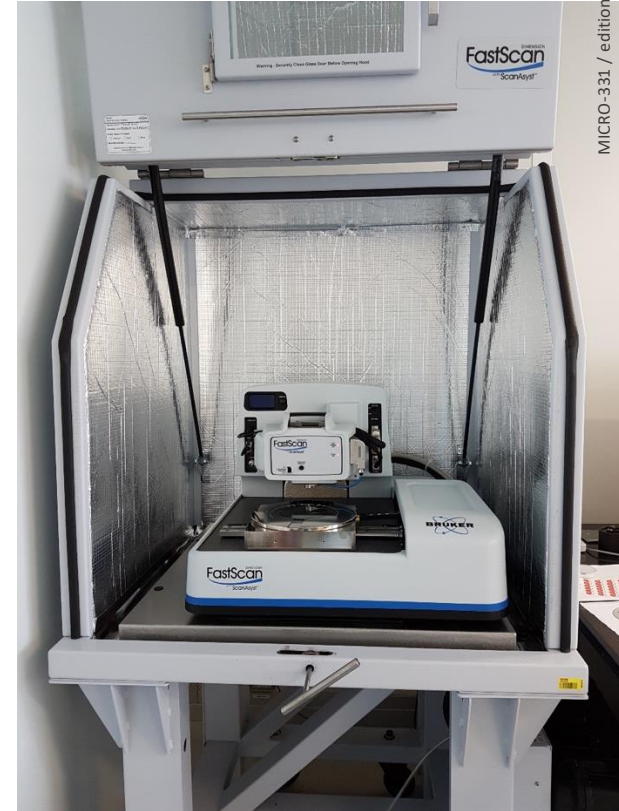


SEM image of the bi-morph
@ 3 keV and 45 degrees tilt



SEM image to indicate where the
surface roughness is measured

Atomic Force Microscope: AFM



3 types of Microscopes

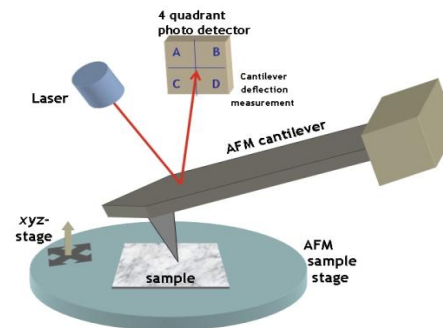
Probing a surface / detecting the reaction



Optical ("light") microscope
'Probe': Light that is reflected from or transmitted through sample.



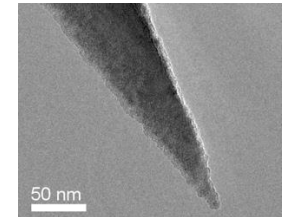
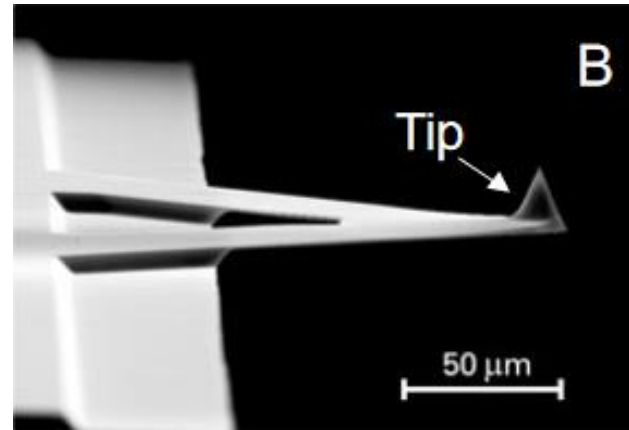
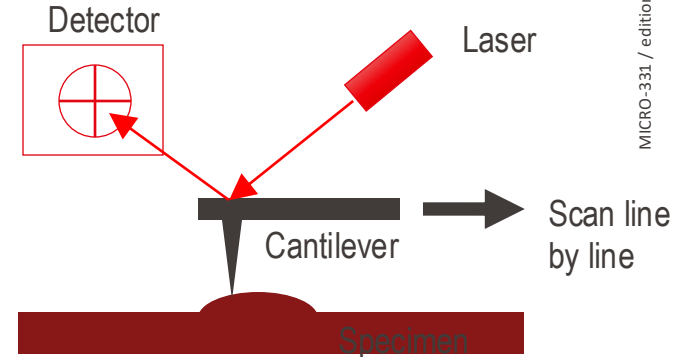
Electron microscope
'Probe': Electrons (shorter wavelength) that are re-emitted from or transmitted through sample.



Scanning Probe microscope
'Probe': tip that interacts locally with surface (force, electrons, photons)

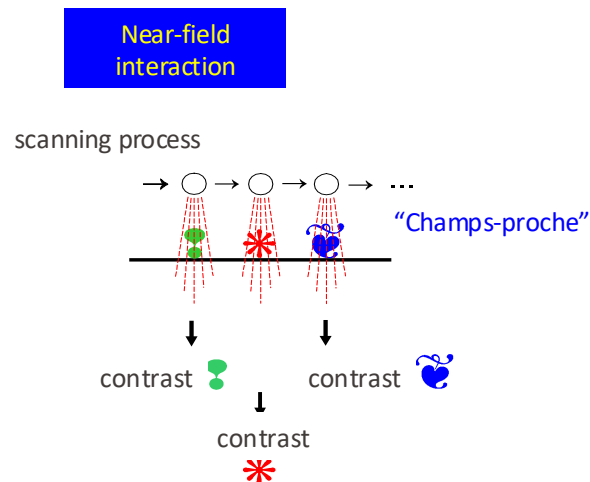
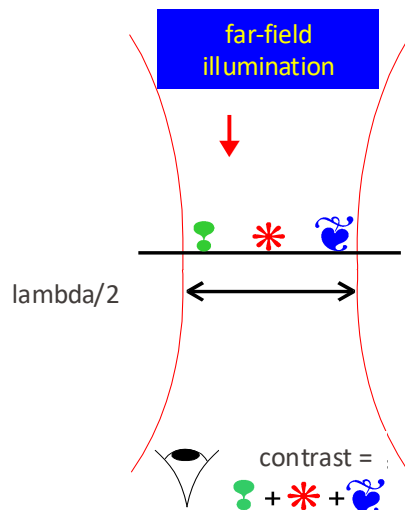
Atomic force microscopy

- A cantilever probe to touch and scan the surface
- Surface height $\rightarrow$ probe position $\rightarrow$ laser signal
- Z resolution: $\sim 0.1\text{nm}$
- XY lateral resolution: $< 10\text{nm}$
- Nano scale 3D surface profile map
- Surface roughness measurement



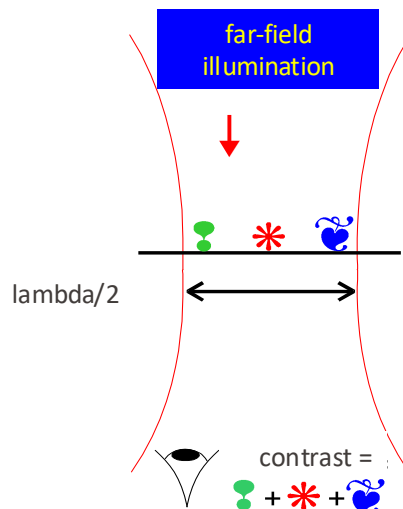
Scanning Probe Microscopy

- conventional microscopy
 - wavelength
 - resolution prop. λ
- probe microscopy
 - spatial dimension
 - resolution = $f(a, d, \dots)$

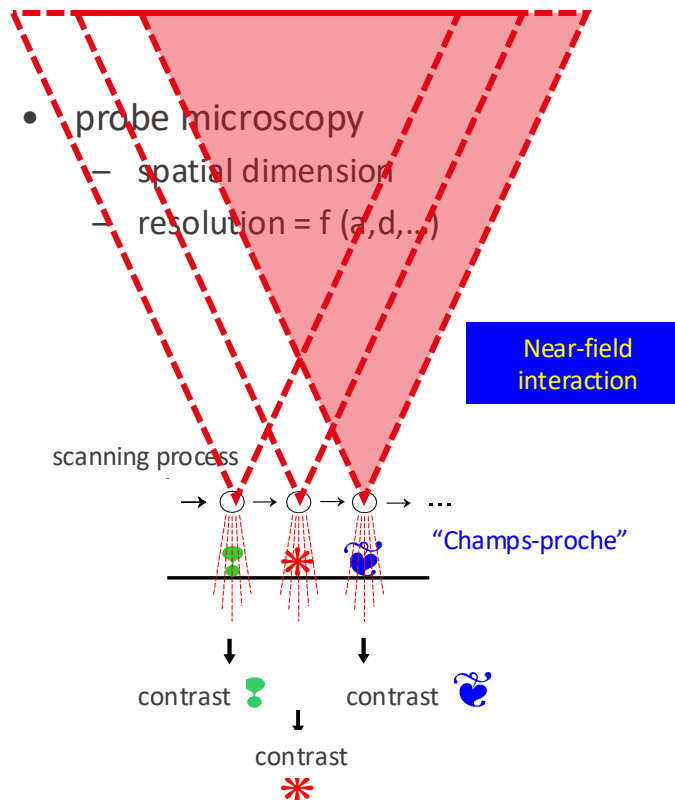


Scanning Probe Microscopy

- conventional microscopy
 - wavelength
 - resolution prop. λ



- probe microscopy
 - spatial dimension
 - resolution = $f(a, d, \dots)$



- Cantilever = force transducer
- Important parameters
- Spring constant k
- Resonance frequency f
- Practical values
- E : Young's modulus (material constant) $E_{\text{Si}} = 1.7 \text{ E}11 \text{ N/m}^2$
- I : cross sectional moment of inertia (square cross section $I = w t^3/12$)

Forces: Micro/nano/pico Newton

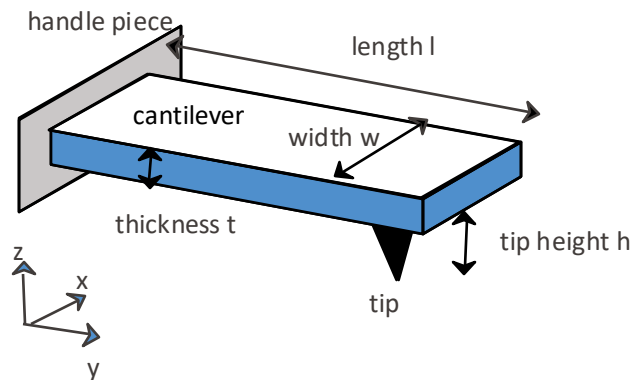
general

$$k = 3 E I / L^3$$

$$f = \frac{1}{2\pi} \sqrt{\frac{k}{m_{\text{eff}}}}$$

Rectangular
shape

$$k = \frac{E w t^3}{4 l^3}$$

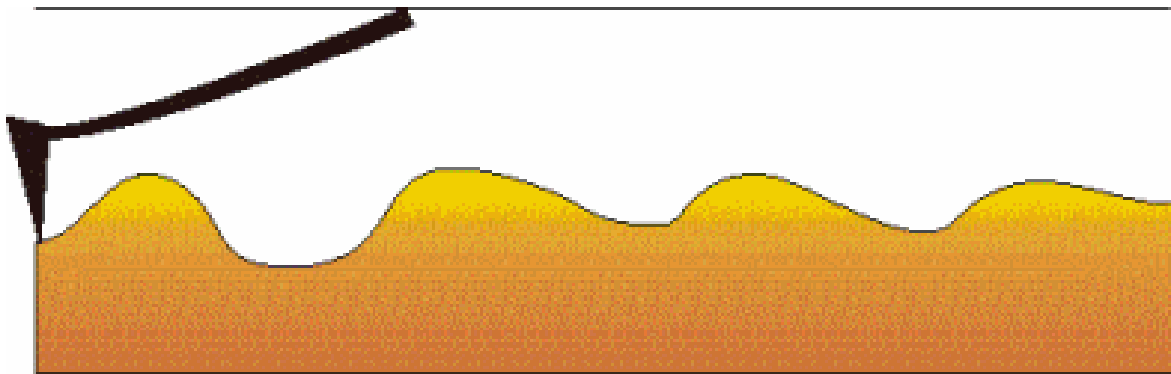


k : 0.01-10 N/m

f : > 10kHz

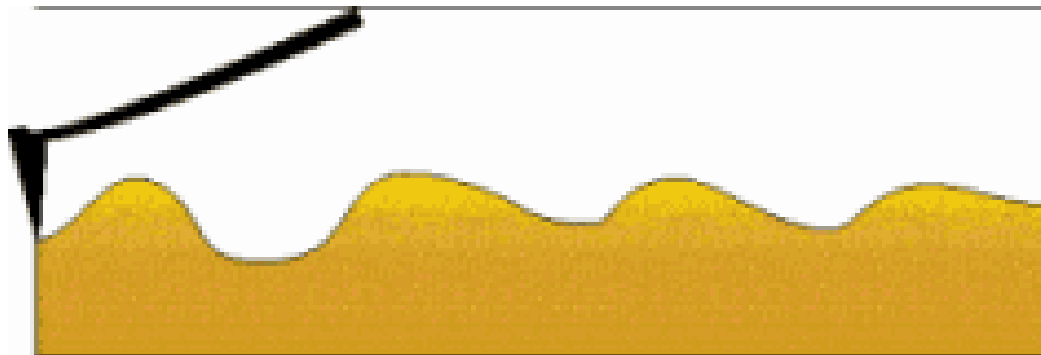
Contact mode SFM/AFM (constant height)

- Constant height (no z-axis actuation)
- Cantilever is bending
- Contact force is modulated
- Risk of tip and/or sample damage

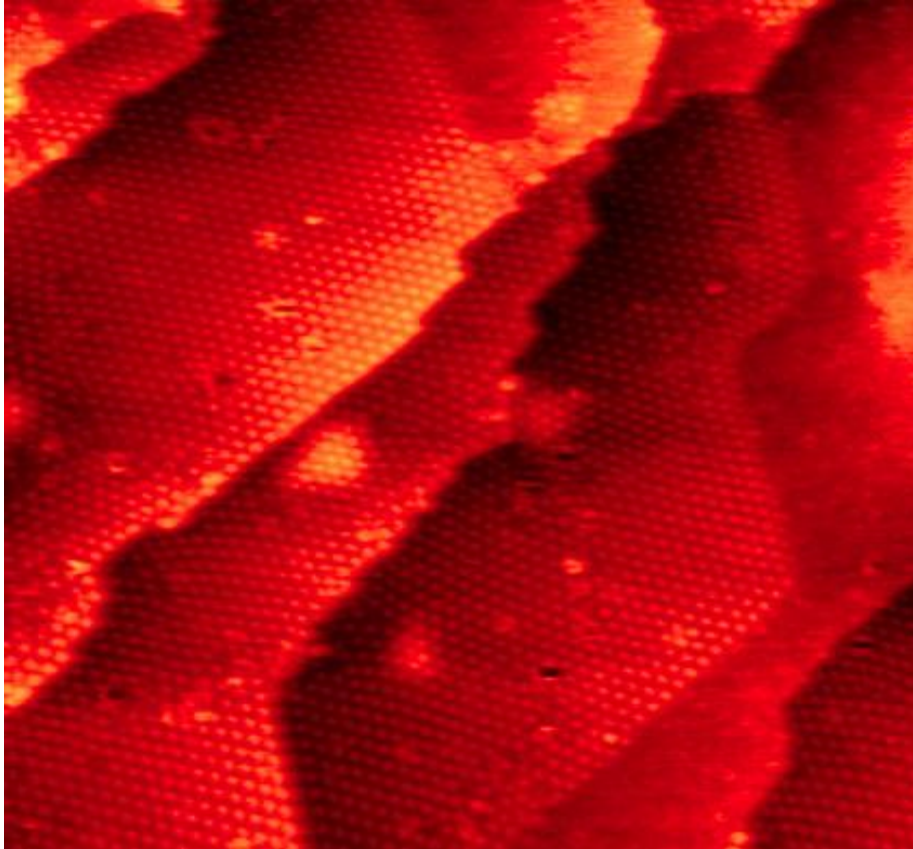


Contact mode SFM/AFM (constant force)

- Constant force during scanning (z-axes actuation)
- Cantilever bending is constant
- Z-feedback moves sample vs. probe
- Avoid tip damage
- Avoid sample damage
- Important for friction force measurements

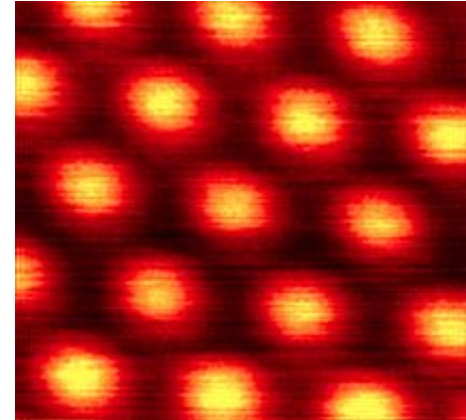


AFM of graphene

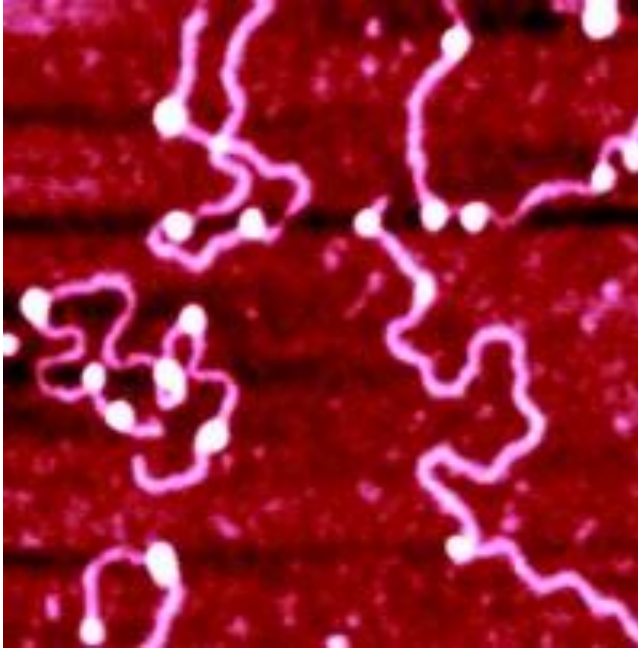


150 nm x 150 nm

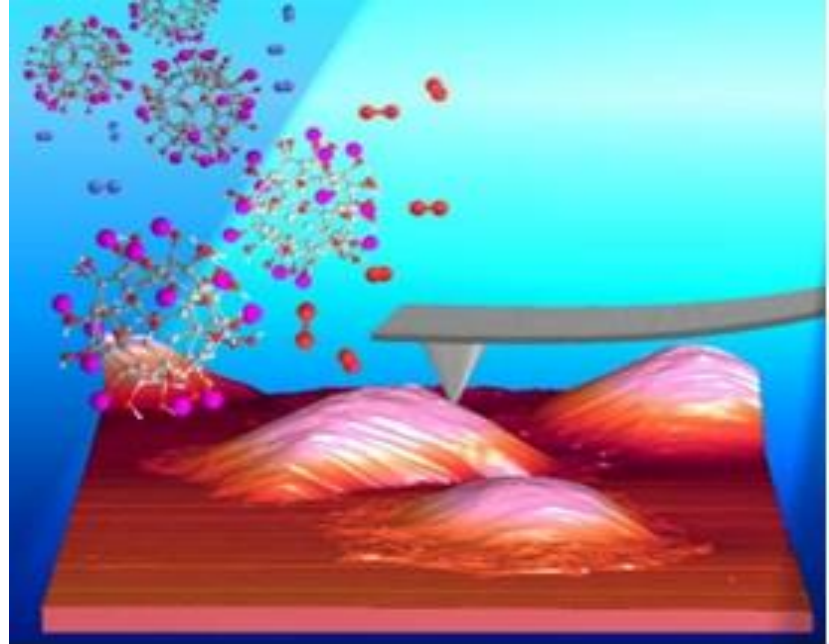
9 nm x 9 nm



Microscopy in biology



DNA molecules

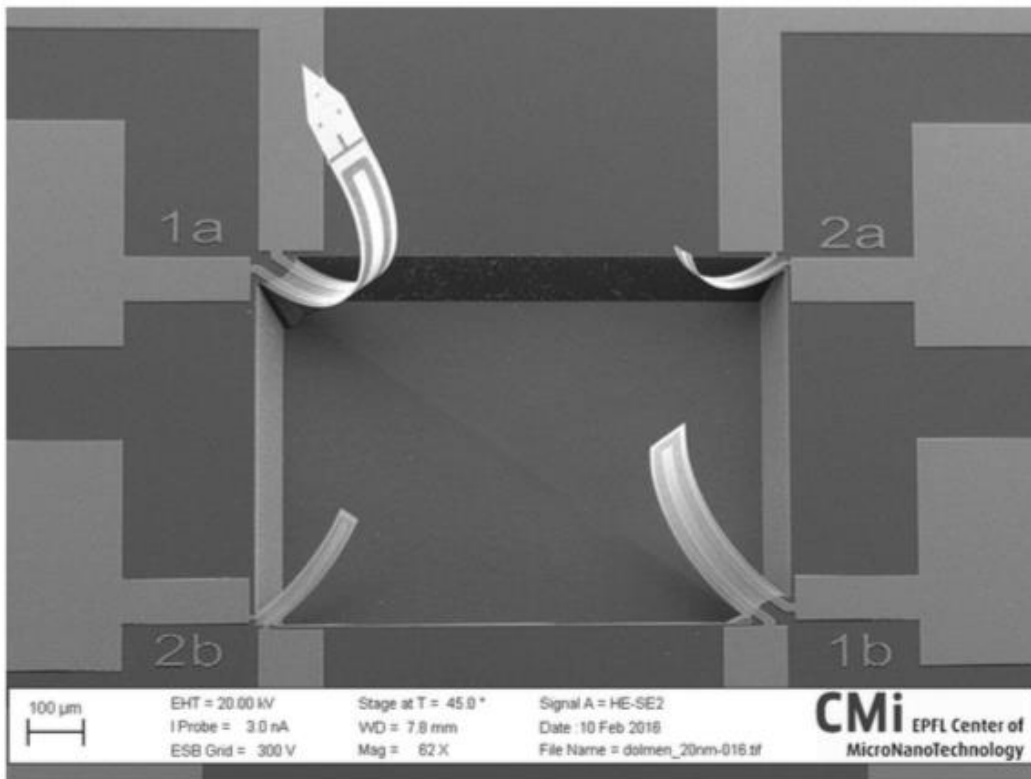


AFM on living cells

Scanning electron microscopy SEM



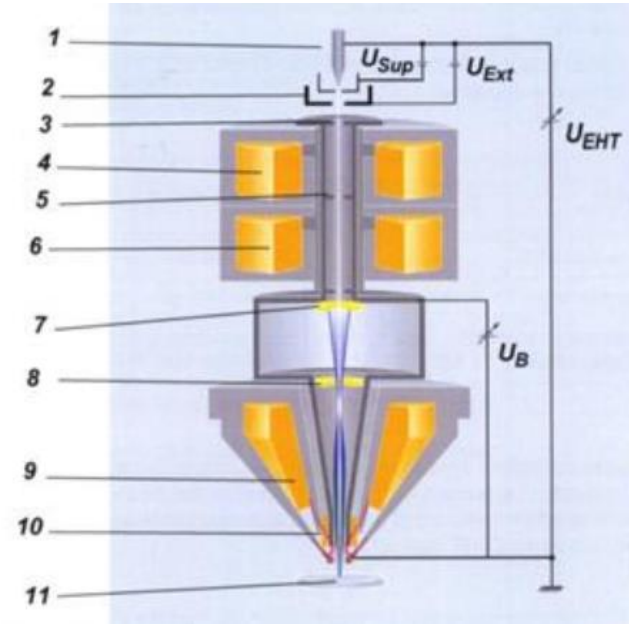
Scanning electron microscopy



Using electron results in higher resolution compared to visible light

Schematics of SEM system

- System similar to EBL:
 - E-gun: 0.02 – 30 kV
 - Electromagnetic lenses
 - Vacuum system
- Electrons → detectors → image
- Morphology & compositional analysis
- Resolution: ~1nm
- Accuracy: +/-3%
- Conductive samples required for high quality imaging

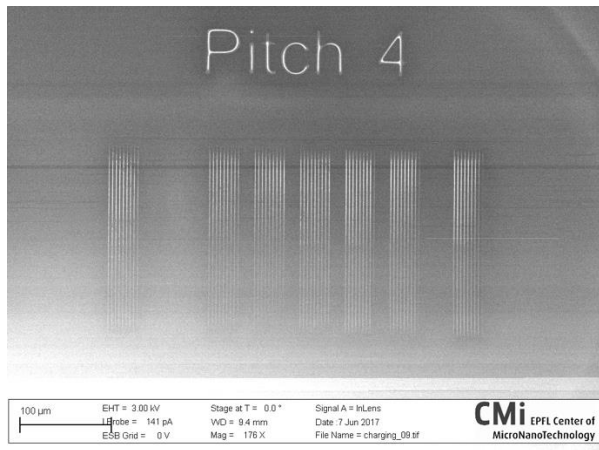


- | | | | |
|----|----------------------|-----|---------------------|
| 1. | Gun | 7. | BSE detector |
| 2. | Extractor | 8. | In-lens SE detector |
| 3. | Anode aperture | 9. | Objective lens |
| 4. | Upper condenser | 10. | Scanning coils |
| 5. | Single hole aperture | 11. | Specimen |
| 6. | Lower condenser | | |

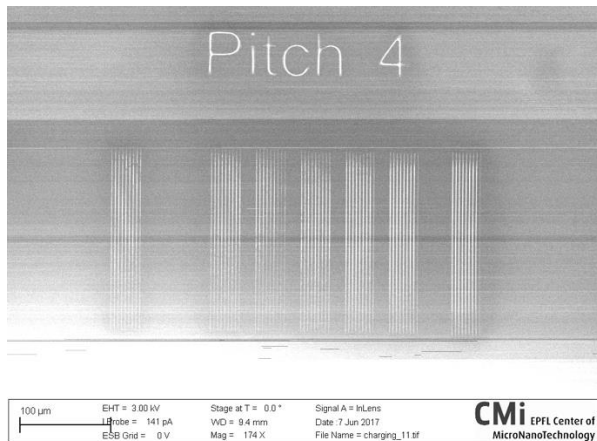
Zeiss The GEMINI II column

Charging issue

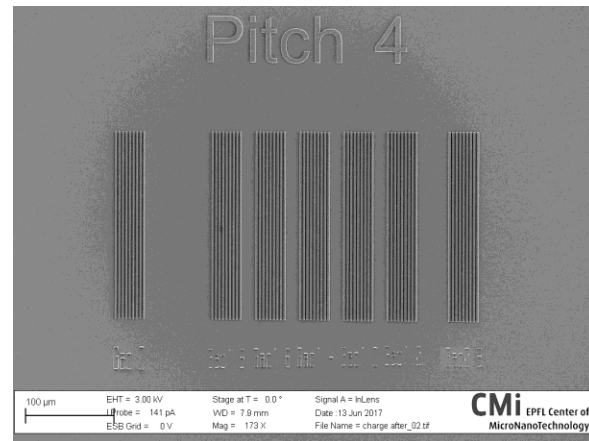
- Electron charges accumulate on the sample and repulse other electrons if the sample is not conductive
- Solution: metal coating (e.g. 20nm Au) + conductive tape



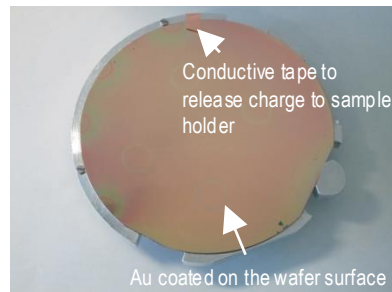
Poor image due to charging
(PR on SiO₂)



Even worse over time
(PR on SiO₂)

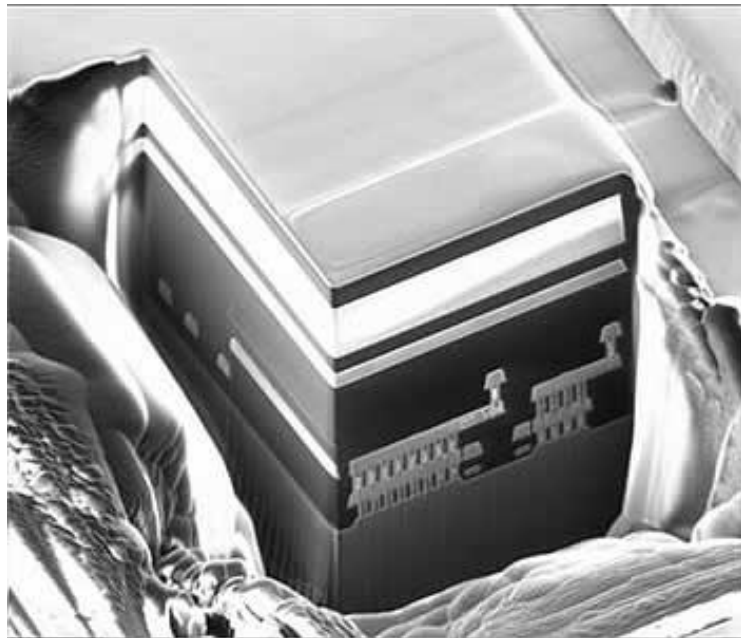


With Au coating

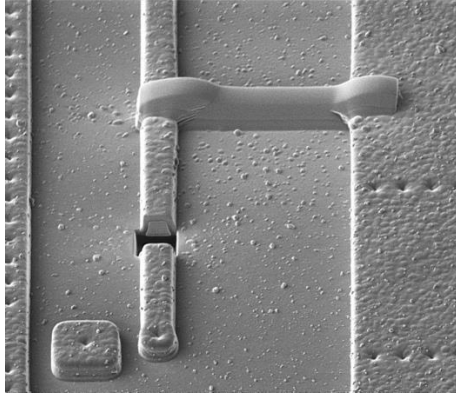


Focused ion beam FIB

Access to inner parts of IC



Gas-Assisted Etching and deposition

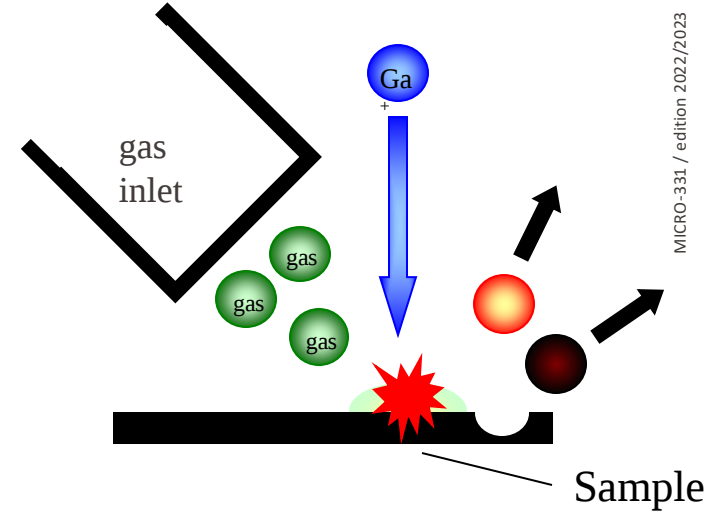


Enhanced milling rate

Redeposition is reduced due to volatile reaction products

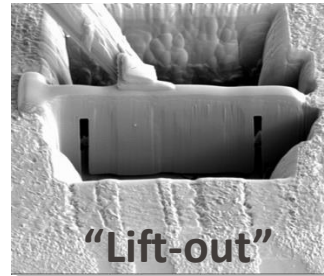
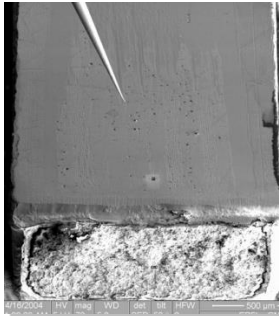
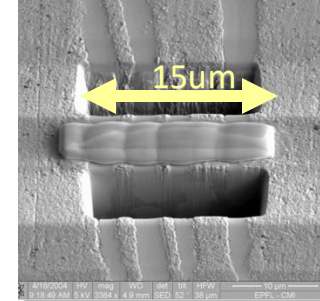
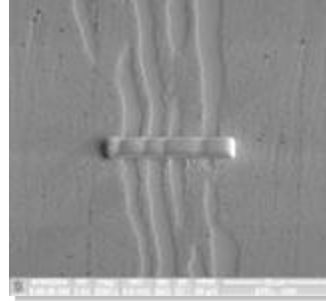
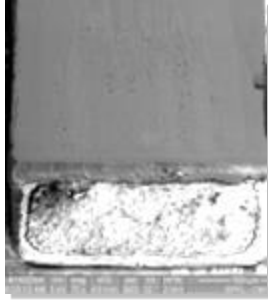
Typical gases: Cl_2 , I_2 , H_2O , XeF_2

Etch enhancement:



	Si	Al	W	SiO_2
Cl_2	7-10	7-10	None	none
XeF_2	7-12	none	7-10	7-10

Applications TEM-lamellas and Lift-out



TEM grid, 3mm diameter

<https://www.youtube.com/watch?v=omcxfWGJzsw>